

DB Plastic-Encapsulate Bridge Rectifier

Features

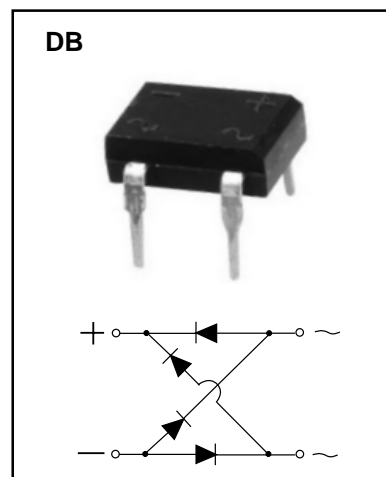
- I_o 2.0A
- V_{RRM} 50V-1000V
- High surge current capability
- Glass passivated chip
- Polarity: Color band denotes cathode

Applications

- General purpose 1 phase Bridge rectifier applications

Marking

- DB20X
- X : From 1 To 7



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	DB2						
				01	02	03	04	05	06	07
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V		35	70	140	280	420	560	700
Average Rectified Output Current	I_o	A	60Hz sine wave, R-load, $T_a=25^\circ\text{C}$	2.0						
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz sine wave, 1 cycle, $T_j=25^\circ\text{C}$	60						
Current Squared Time	I^2t	A^2S	$1\text{ms} \leq t < 8.3\text{ms}$ $T_j=25^\circ\text{C}$, Rating of per diode	15						
Storage Temperature	T_{stg}	$^\circ\text{C}$		-55 ~+150						
Junction Temperature	T_j	$^\circ\text{C}$		-55 ~+150						

Electrical Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	$I_{FM}=2.0\text{A}$, Pulse measurement, Rating of per diode	1.1
Peak Reverse Current	I_{RRM}	μA	$V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode	10
Thermal Resistance	$R_{\theta J-A}$	$^\circ\text{C/W}$	Between junction and ambient, On glass-epoxi substrate	68
	$R_{\theta J-L}$		Between junction and lead	15

Typical Characteristics

FIG1: I_o - T_a Curve

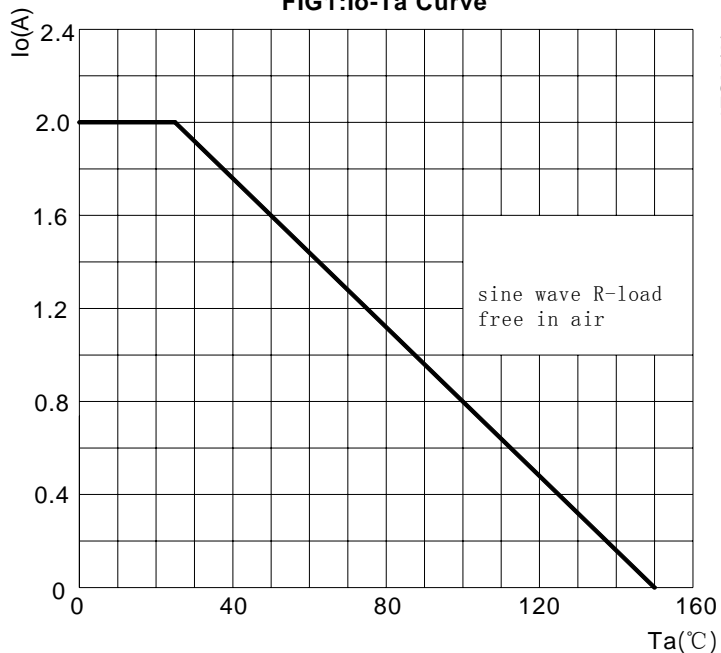
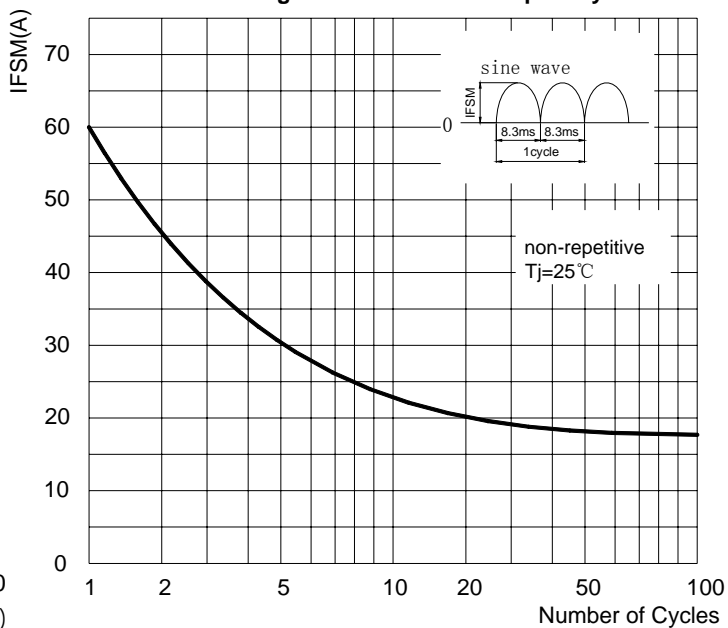


FIG2: Surge Forward Current Capacity



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FIG3: Forward Voltage

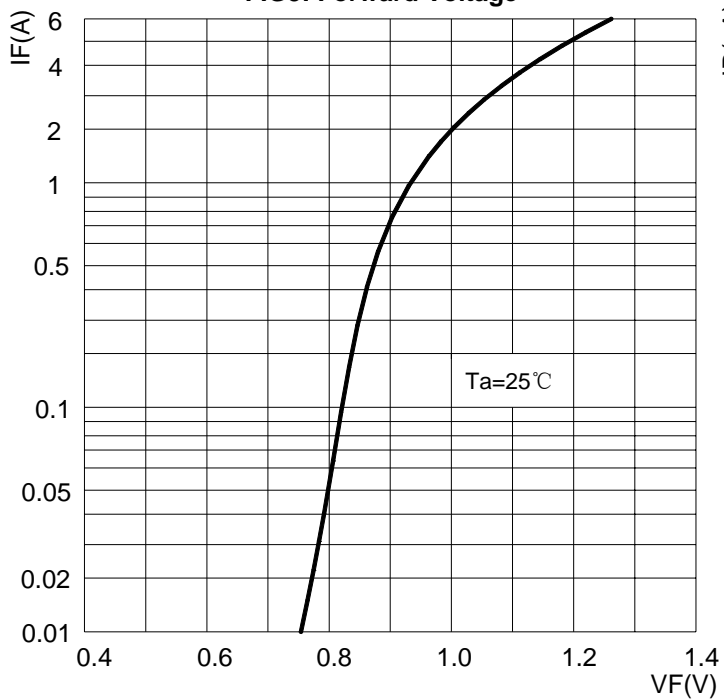
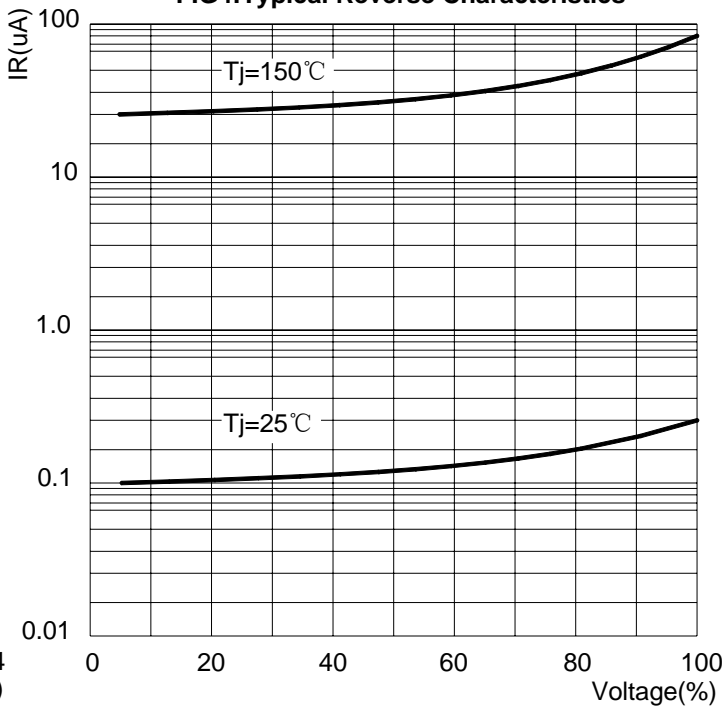
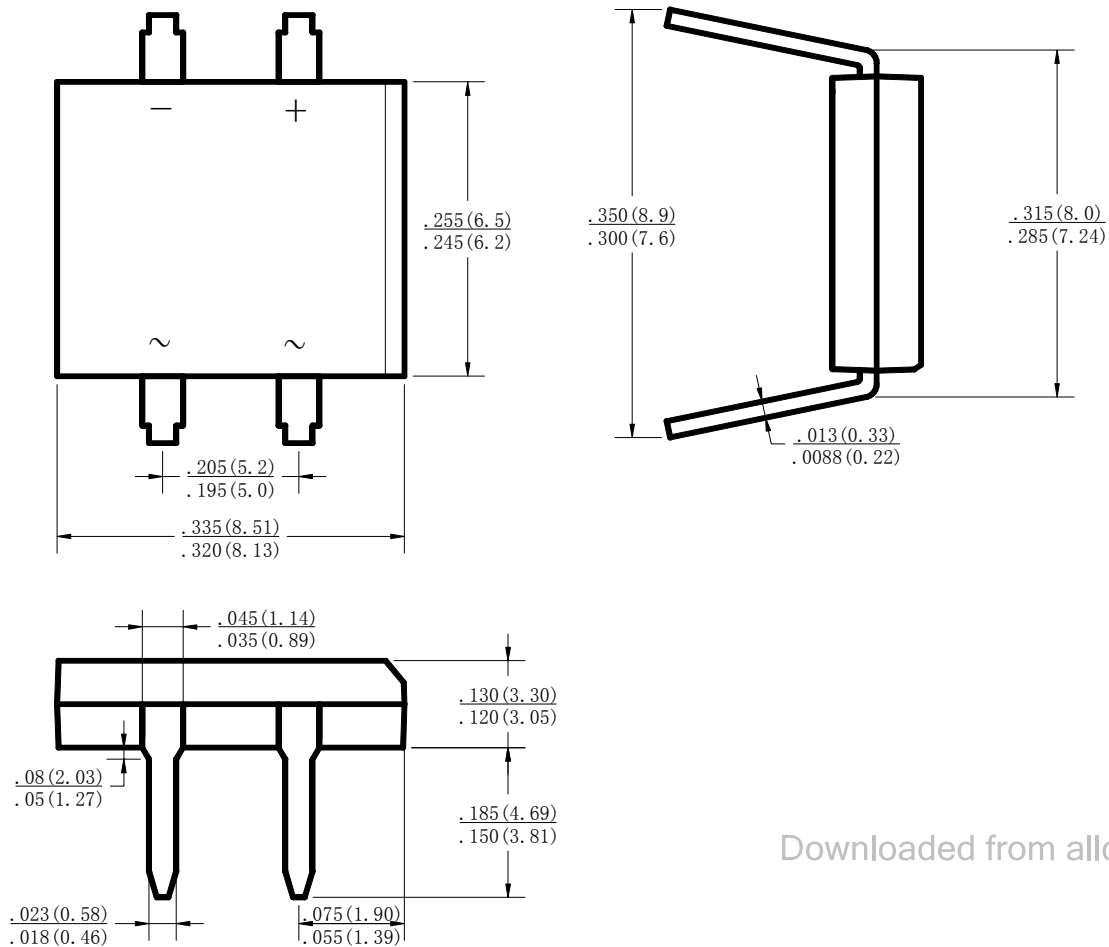


FIG4: Typical Reverse Characteristics



DB Package Outline Dimensions



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Dimensions in inches and (millimeters)

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